

## **SiC JFET Division**

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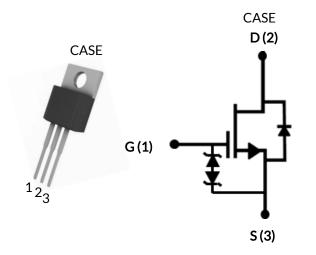








# UJ3C065030T3S



Part Number	Package	Marking			
UJ3C065030T3S	TO-220-3L	UJ3C065030T3S			









# Silicon Carbide (SiC) Cascode JFET -EliteSiC, Power N-Channel, TO-220-3L, 650 V, 27 mohm

Rev. E, January 2025

#### Description

This SiC FET device is based on a unique 'cascode' circuit configuration, in which a normally-on SiC JFET is co-packaged with a Si MOSFET to produce a normally-off SiC FET device. The device's standard gate-drive characteristics allows for a true "drop-in replacement" to Si IGBTs, Si FETs, SiC MOSFETs or Si superjunction devices. Available in the TO-220-3L package, this device exhibits ultralow gate charge and exceptional reverse recovery characteristics, making it ideal for switching inductive loads and any application requiring standard gate drive.

#### **Features**

- Typical on-resistance R<sub>DS(on),typ</sub> of 27mΩ
- Maximum operating temperature of 175°
- Excellent reverse recovery
- Low gate charge
- Low intrinsic capacitance
- ESD protected, HBM class 2
- AECQ Qualified

#### **Typical applications**

- EV charging
- PV inverters
- Switch mode power supplies
- Power factor correction modules
- Motor drives
- Induction heating













### **Maximum Ratings**

Parameter	Symbol	Test Conditions	Value	Units
Drain-source voltage	$V_{DS}$		650	V
Gate-source voltage	$V_{GS}$	DC	-25 to +25	V
Continuous drain current <sup>1</sup>		T <sub>C</sub> = 25°C	85	Α
Continuous drain current	I <sub>D</sub>	T <sub>C</sub> = 100°C	62	Α
Pulsed drain current <sup>2</sup>	I <sub>DM</sub>	T <sub>C</sub> = 25°C	230	А
Single pulsed avalanche energy <sup>3</sup>	E <sub>AS</sub>	L=15mH, I <sub>AS</sub> =4A	120	mJ
Power dissipation	P <sub>tot</sub>	T <sub>C</sub> = 25°C	441	W
Maximum junction temperature	$T_{J,max}$		175	°C
Operating and storage temperature	$T_J, T_{STG}$		-55 to 175	°C
Max. lead temperature for soldering, 1/8" from case for 5 seconds	T <sub>L</sub>		250	°C

- 1. Limited by  $T_{J,max}$
- 2. Pulse width  $t_p$  limited by  $T_{J,max}$
- 3. Starting  $T_J = 25^{\circ}C$

#### **Thermal Characteristics**

Doromotor	Symbol	Test Conditions		Value	Units	
Parameter	Зуппон	rest Conditions	Min	Тур	Max	Units
Thermal resistance, junction-to-case	$R_{\theta JC}$			0.26	0.34	°C/W













## Electrical Characteristics (T<sub>J</sub> = +25°C unless otherwise specified)

### Typical Performance - Static

Parameter	Symbol	Test Conditions		Units		
			Min	Тур	Max	Ullits
Drain-source breakdown voltage	BV <sub>DS</sub>	$V_{GS}$ =0V, $I_D$ =1mA	650			V
Total drain leakage current		V <sub>DS</sub> =650V, V <sub>GS</sub> =0V, T <sub>J</sub> =25°C		6	150	- μΑ
	I <sub>DSS</sub>	V <sub>DS</sub> =650V, V <sub>GS</sub> =0V, T <sub>J</sub> =175°C		30		
Total gate leakage current	I <sub>GSS</sub>	V <sub>DS</sub> =0V, T <sub>J</sub> =25°C, V <sub>GS</sub> =-20V / +20V		6	±20	μА
		V <sub>GS</sub> =12V, I <sub>D</sub> =50A, T <sub>J</sub> =25°C		27	35	
Drain-source on-resistance	R <sub>DS(on)</sub>	V <sub>GS</sub> =12V, I <sub>D</sub> =50A, T <sub>J</sub> =125°C		35		mΩ
		V <sub>GS</sub> =12V, I <sub>D</sub> =50A, T <sub>J</sub> =175°C		43		
Gate threshold voltage	$V_{G(th)}$	$V_{DS}$ =5V, $I_D$ =10mA	4	5	6	V
Gate resistance	$R_{G}$	f=1MHz, open drain		4.5		Ω

## Typical Performance - Reverse Diode

Parameter	Symbol	Test Conditions		Units			
			Min	Тур	Max	Units	
Diode continuous forward current <sup>1</sup>	I <sub>S</sub>	T <sub>C</sub> =25°C			85	Α	
Diode pulse current <sup>2</sup>	$I_{S,pulse}$	T <sub>C</sub> =25°C			230	Α	
Forward voltage	V <sub>FSD</sub>	V <sub>GS</sub> =0V, I <sub>F</sub> =20A, T <sub>J</sub> =25°C		1.3	1.4	V	
		V <sub>GS</sub> =0V, I <sub>F</sub> =20A, T <sub>J</sub> =175°C		1.35			
Reverse recovery charge	Q <sub>rr</sub>	$Q_{rr}$	$V_R$ =400V, $I_F$ =50A, $V_{GS}$ =0V, $R_{G_EXT}$ =20 $\Omega$		400		nC
Reverse recovery time	t <sub>rr</sub>	di/dt=1550A/μs, Τ <sub>J</sub> =150°C		33		ns	













# Typical Performance - Dynamic

Parameter	Symbol	Test Conditions	Value			Units
Parameter	Symbol rest conditions		Min	Тур	Max	Offics
Input capacitance	$C_{iss}$	V -100V/V -0V/		1500		
Output capacitance	C <sub>oss</sub>	V <sub>DS</sub> =100V, V <sub>GS</sub> =0V f=100kHz		320		pF
Reverse transfer capacitance	$C_{rss}$	1-100KHZ		2.3		
Effective output capacitance, energy related	C <sub>oss(er)</sub>	$V_{DS}$ =0V to 400V, $V_{GS}$ =0V		230		pF
Effective output capacitance, time related	$C_{oss(tr)}$	$V_{DS}$ =0V to 400V, $V_{GS}$ =0V		520		pF
C <sub>OSS</sub> stored energy	$E_{oss}$	V <sub>DS</sub> =400V, V <sub>GS</sub> =0V		18.5		μЈ
Total gate charge	$Q_{G}$	- V <sub>DS</sub> =400V, I <sub>D</sub> =50A, - V <sub>GS</sub> = -5V to 15V		51		nC
Gate-drain charge	$Q_{GD}$			11		
Gate-source charge	$Q_{GS}$			19		
Turn-on delay time	$t_{d(on)}$			36		
Rise time	$t_r$	$V_{DS}$ =400V, $I_{D}$ =50A, Gate		22		nc
Turn-off delay time	t <sub>d(off)</sub>	Driver =-5V to +15V,		56		ns
Fall time	t <sub>f</sub>	Turn-on $R_{G,EXT}$ =1 $\Omega$ , Turn-off $R_{G,EXT}$ =20 $\Omega$		15		
Turn-on energy	E <sub>ON</sub>	Inductive Load, FWD: UJ3D065030TS, $T_J$ =150°C		472		
Turn-off energy	E <sub>OFF</sub>			257		μЈ
Total switching energy	E <sub>TOTAL</sub>			729		د م





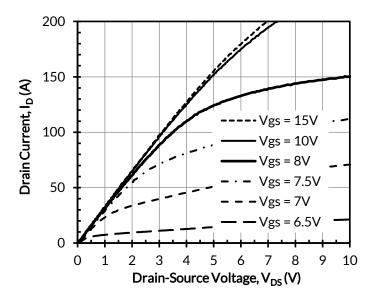








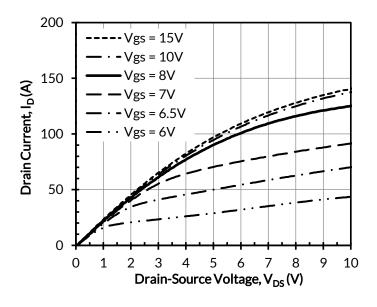
#### **Typical Performance Diagrams**



200 150 Drain Current, I<sub>D</sub> (A) 100 Vgs = 15V Vgs = 10V Vgs = 8V 50 - Vgs = 7V Vgs = 6.5V 0 1 2 3 5 10 Drain-Source Voltage,  $V_{DS}(V)$ 

Figure 1. Typical output characteristics at  $T_J = -55$ °C, tp < 250 $\mu$ s

Figure 2. Typical output characteristics at  $T_J = 25$ °C, tp < 250 $\mu$ s



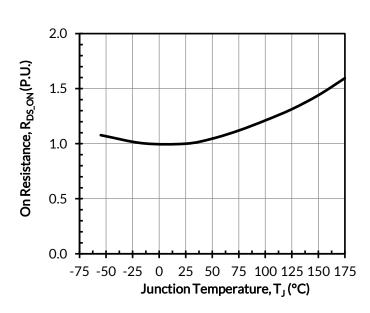


Figure 3. Typical output characteristics at  $T_J$  = 175°C, tp < 250 $\mu$ s

Figure 4. Normalized on-resistance vs. temperature at  $V_{GS}$  = 12V and  $I_D$  = 50A



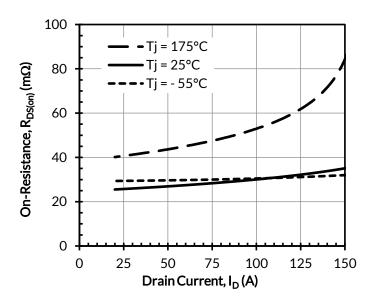












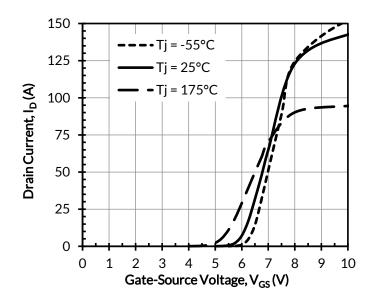
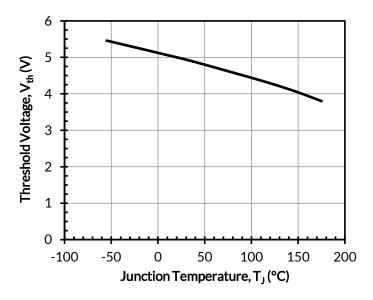


Figure 5. Typical drain-source on-resistances at  $V_{\text{GS}}$  = 12V

Figure 6. Typical transfer characteristics at  $V_{DS}$  = 5V



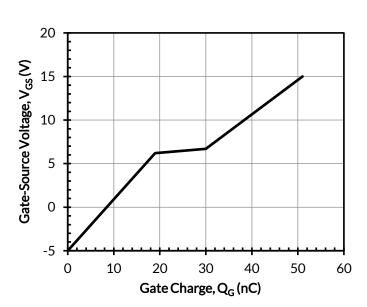


Figure 7. Threshold voltage vs. junction temperature at  $V_{DS}$  = 5V and  $I_{D}$  = 10mA

Figure 8. Typical gate charge at  $V_{DS}$  = 400V and  $I_{D}$  = 50A













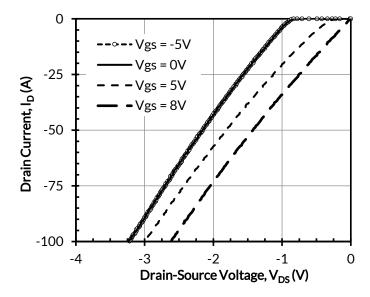


Figure 9. 3rd quadrant characteristics at  $T_J$  = -55°C

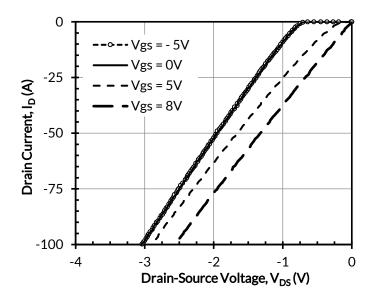


Figure 10. 3rd quadrant characteristics at T<sub>J</sub> = 25°C

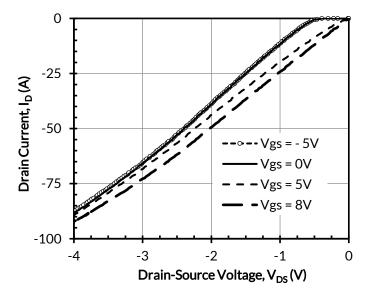


Figure 11. 3rd quadrant characteristics at  $T_J = 175$ °C

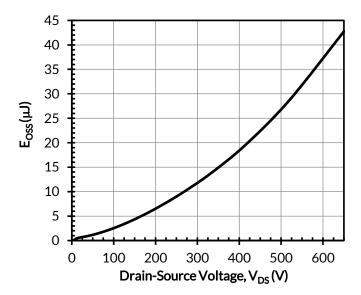


Figure 12. Typical stored energy in  $C_{OSS}$  at  $V_{GS} = 0V$ 



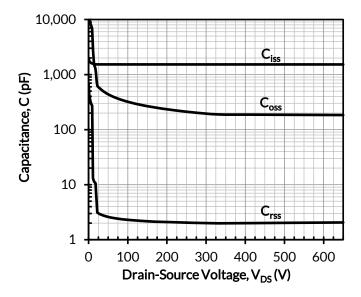












100 80 -75 -50 -25 0 25 50 75 100 125 150 175 Case Temperature, T<sub>c</sub> (°C)

Figure 13. Typical capacitances at f = 100kHz and  $V_{GS} = 0V$ 

Figure 14. DC drain current derating

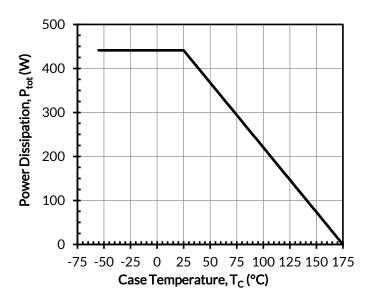


Figure 15. Total power dissipation

Figure 16. Maximum transient thermal impedance













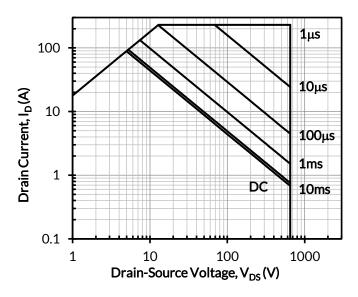


Figure 17. Safe operation area at  $T_C = 25$ °C, D = 0, Parameter  $t_p$ 

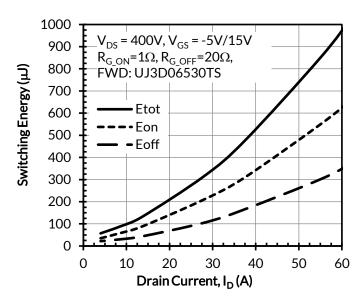


Figure 18. Clamped inductive switching energy vs. drain current at  $T_J = 150$ °C

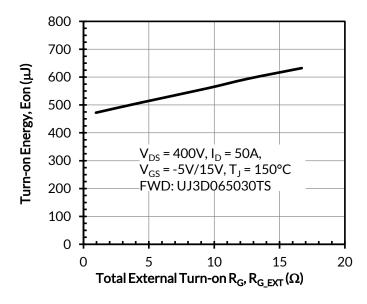


Figure 19. Clamped inductive switching turn-on energy vs.  $R_{G,EXT\_ON}$ 

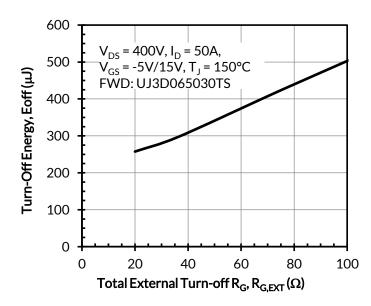


Figure 20. Clamped inductive switching turn-off energy vs.  $R_{G,EXT\_OFF}$ 













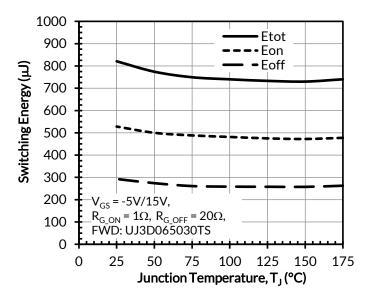


Figure 21. Clamped inductive switching energy vs. junction temperature at  $V_{DS}$  =400V and  $I_D$  = 50A

#### **Applications Information**

SiC FETs are enhancement-mode power switches formed by a high-voltage SiC depletion-mode JFET and a low-voltage silicon MOSFET connected in series. The silicon MOSFET serves as the control unit while the SiC JFET provides high voltage blocking in the off state. This combination of devices in a single package provides compatibility with standard gate drivers and offers superior performance in terms of low on-resistance ( $R_{DS(on)}$ ), output capacitance ( $C_{oss}$ ), gate charge ( $Q_G$ ), and reverse recovery charge ( $Q_{rr}$ ) leading to low conduction and switching losses. The SiC FETs also provide excellent reverse conduction capability eliminating the need for an external anti-parallel diode.

Like other high performance power switches, proper PCB layout design to minimize circuit parasitics is strongly recommended due to the high dv/dt and di/dt rates. An external gate resistor is recommended when the FET is working in the diode mode in order to achieve the optimum reverse recovery performance. For more information on SiC FET operation, see www.unitedsic.com.

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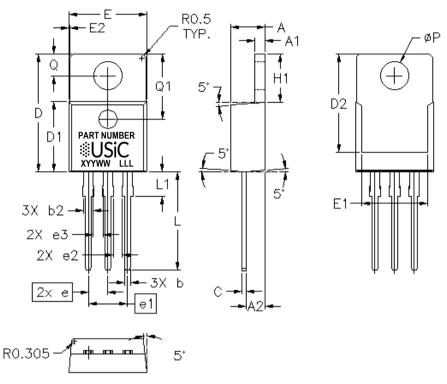
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# TO-220-3L PACKAGE OUTLINE, PART MARKING AND TUBE SPECIFICATIONS

# **PACKAGE OUTLINE**

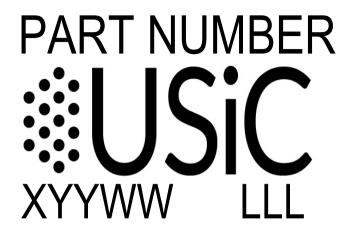


DIM	INC	HES	METERS		
	MIN	MAX	MIN	MAX	
Α	0.140	0.190	3.56	4.83	
A1	0.020	0.055	0.51	1.40	
A2	0.080	0.115	2.03	2.92	
b	0.015	0.040	0.38	1.02	
b2	0.045	0.070	1.14	1.78	
С	0.014	0.024	0.36	0.61	
D	0.560	0.650	14.22	16.51	
D1	0.330	0.355	8.38	9.02	
D2	0.480	0.507	12.19	12.88	
E	0.380	0.420	9.65	10.67	
е	0.100 BSC		2.54 BSC		
e1	0.200 BSC		5.08 BSC		
E1	0.270	0.350	6.86	8.89	
E2	-	0.030	-	0.76	
L	0.500	0.580	12.70	14.73	
L1	-	0.250	-	6.35	
ØΡ	0.139	0.161	3.53	4.09	
Н	0.230	0.270	5.84	6.86	
Q	0.100	0.135	2.54	3.43	
Q1	0.330	0.340	8.38	8.64	



# TO-220-3L PACKAGE OUTLINE, PART MARKING AND TUBE SPECIFICATIONS

### **PART MARKING**



PART NUMBER = REFER TO
DS PN DECODER FOR DETAILS

X = ASSEMBLY SITE

YY = YEAR

WW = WORK WEEK

LLL = LOT ID

#### **PACKING TYPE**

**ANTI-STATIC TUBE** 

**QUANTITY /TUBE: 50 UNITS** 

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